

Composition Table

Product(Pb-free): XCL205xxxxAR-G
Typical Mass: 20 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number	
Coil	Core (Ferrite)	7.706	Iron oxide	385300	1309-37-1	
		2.371	Zinc oxide	118600	1314-13-2	
		1.304	Nickel oxide	65200	1313-99-1	
		0.474	Copper oxide	23700	1317-38-0	
	Base substrate	0.105	Bismaleimide triazine resin / Epoxy Resin	5300	-	
		0.068	Inorganic filler	3400	-	
		0.203	Fiberglass	10100	65997-17-3	
	Overcoating Resin A (Inter layer)	0.054	Epoxy resin	2700	25068-38-6	
		0.121	Silica	6000	-	
	Overcoating Resin B (Top coating)	0.043	Epoxy resin	2200	25068-38-6	
		0.096	Silica	4800	-	
	Adhesive Resin	0.290	Epoxy resin	14500	25068-38-6	
		0.646	Silica	32300	-	
	Conductor	2.340	Copper	117000	7440-50-8	
	Plating	0.043	Nickel	2200	7440-02-0	
		0.118	Tin	5900	7440-31-5	
	Adhesive Resin	0.012	Epoxy resin	600	-	
		0.007	Silica	400	14808-60-7	
	IC	Silicon chip	0.433	Silicon	21700	7440-21-3
			-	Arsenic	<1	7440-38-2
Lead-pad		1.223	Nickel	61100	7440-02-0	
		0.113	Silver	5700	7440-22-4	
		0.022	Gold	1100	7440-57-5	
Die attach		0.023	Epoxy resin	1200	-	
		0.018	Silica	900	60676-86-0	
Bonding wire		0.071	Gold	3500	7440-57-5	
Resin		1.626	Silica	81300	60676-86-0	
		0.165	Epoxy resin	8300	-	
		0.155	Phenol resin	7800	-	
		0.151	Metal hydroxide	7500	-	

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."